1-2199298-1 ACTIVE

DIPLOMATE

TE Internal #: 1-2199298-1

Stamped & Formed, 6 Position, Low Profile, Through Hole, Tin (Sn),

-40 - 105 °C [-40 - 221 °F], DIP Sockets

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Connectors > Socket Connectors > IC Sockets > DIP Sockets



Contact Fabrication: Stamped & Formed

Number of Positions: 6
Connector Profile: Low

Row-to-Row Spacing: 7.62 mm [.3 in]

Leg Style: Through Hole

Features

Product Type Features

Leg Style	Through Hole
Configuration Features	

PCB Mount Orientation	Vertical
Number of Rows	2
Number of Positions	6

Electrical Characteristics

Contact Resistance	20 mΩ
Insulation Resistance	1000 ΜΩ

Body Features

Sleeve Plating Material	Tin/Lead
Frame Style	Closed, Ladder
Sleeve Material	Brass/Copper
Connector Profile	Low

Contact Features

Mating Contact Type	Dual Leaf
Contact Base Material	Phosphor Bronze
IC Socket Type	DIP



PCB Contact Termination Area Plating Material	Tin
Contact Type	Pin
Contact Fabrication	Stamped & Formed
Contact Mating Area Plating Material	Tin (Sn)
	60 μin
Contact Current Rating (Max)	1 A
Termination Features	
Termination Method to PCB	Through Hole - Solder
	3 in
Mechanical Attachment	
Connector Mounting Type	Board Mount
Mating Alignment Type	Polarization
Mating Alignment	With
Housing Features	
Housing Color	Black
Housing Material	PBT GF30
Centerline (Pitch)	2.54 mm[.1 in]
Dimensions	
Product Length	7.62 mm[.3 in]
Profile Height from PCB	5.1 mm[.2 in]
Row-to-Row Spacing	7.62 mm[.3 in]
Usage Conditions	
Operating Temperature Range	-40 - 105 °C[-40 - 221 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Tubes per Box	2
Packaging Method	Box & Tube, Tube
Packaging Quantity	80



Other

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Out of Scope
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Customers Also Bought



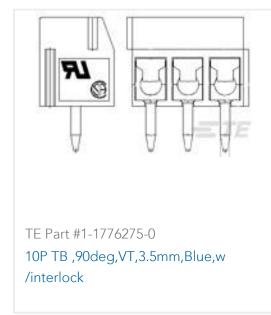




















Documents

Product Drawings

6P,DIP SKT,300 CL,LDR,PB FREE

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1-2199298-1_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1-2199298-1_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1-2199298-1_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

DIP Sockets Quick Reference Guide (EN)

English